Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment
Marketing Name / Model [List multiple models if applicable.]
HP FF 12904E 2.5Tbps Type F Fabric Mod(JH264A)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sqcm	2
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardantsweighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0

Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screw driver	2#
Sleeve	M3

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove the film 1.
2. Unscrew the screws on part 2, and then remove part 2.
3. Unscrew the screws on heatsink 3, and then remove heatsink 3.
4. Unscrew the screws on part 4, and then remove part 4.
5. Unscrew the screws on PCB 5, and then remove PCB 5.
6. Unscrew the screws on PCB 5, and then remove part 5-2&5-3.
7. Unscrew the screws on part 6, and then remove part 7&8.
8. Unscrew the screws on part 8-1, and then remove part 8-1&8-2&8-3.
9. Remove part 9.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations)

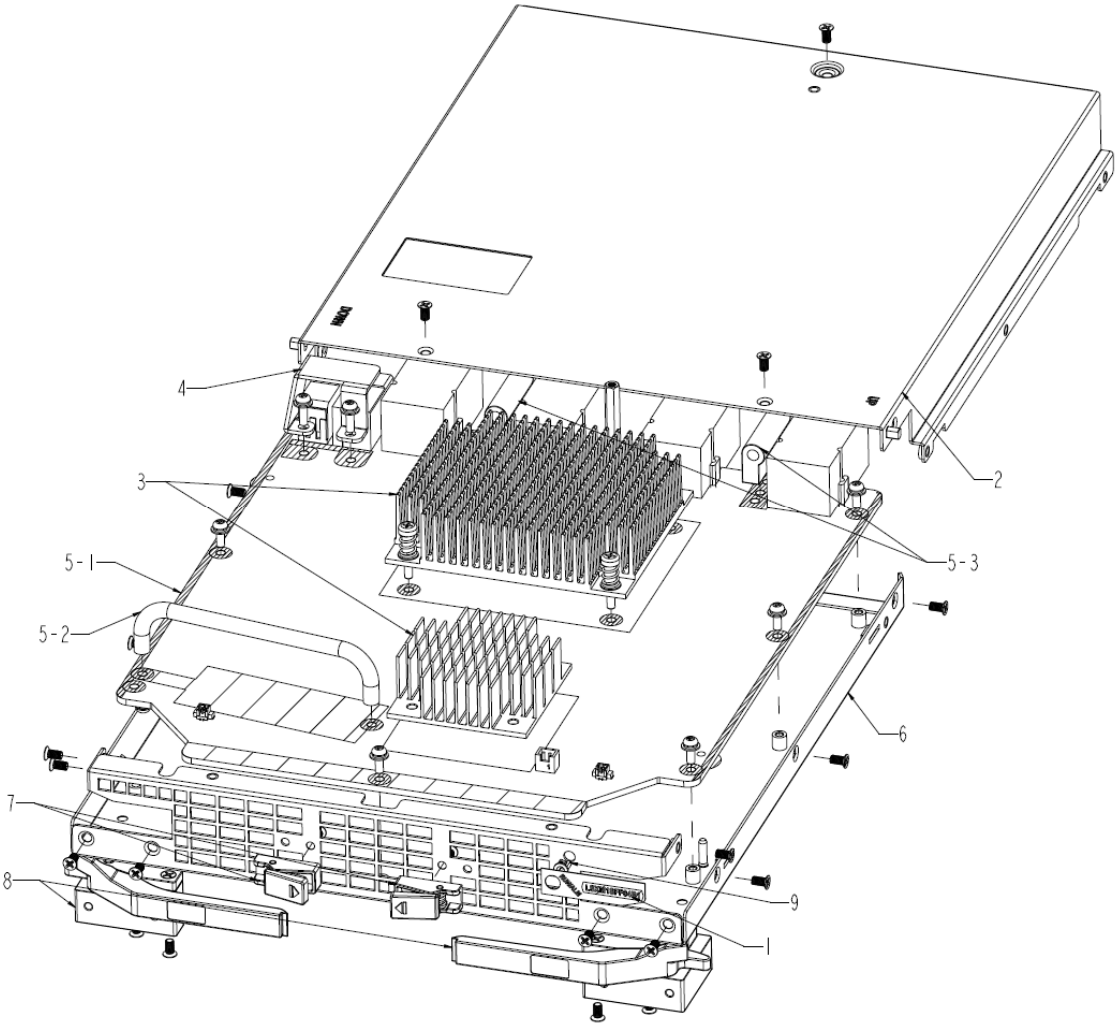

Figure 1 Treatments to the product（front view）

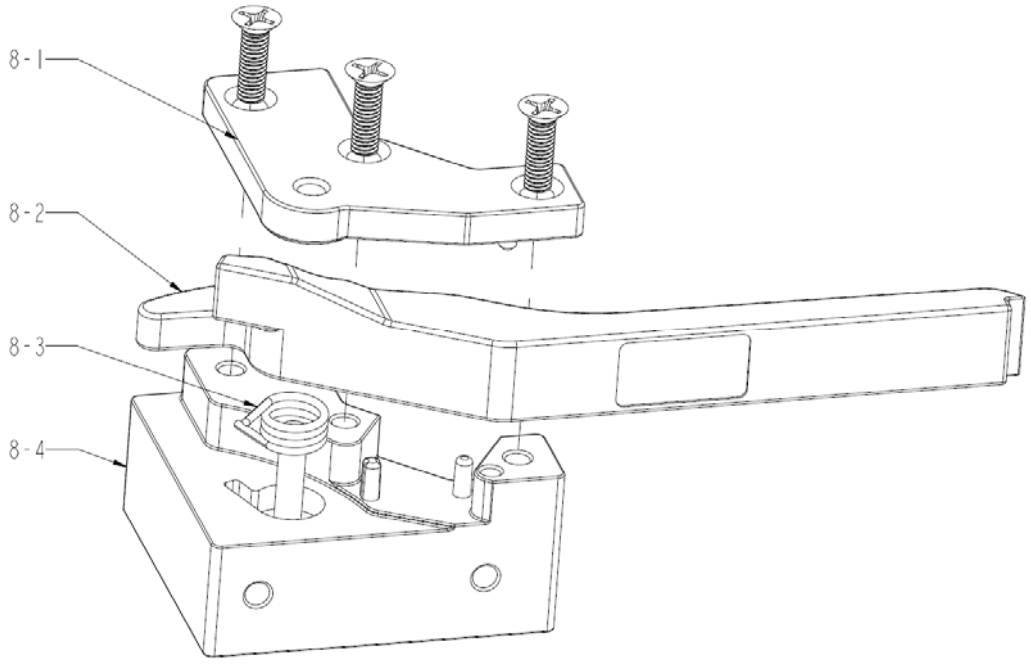

Figure 2 Treatments to part 8

3.3 Material of the facility built

Facility	Components	Material	Weight(g)	Weight percentage	Selective treatment for materials and components	Details
1		PC	0.1	0.01%		Pla recycling
2		Fe	619.1	23.81%		Fe recycling
3		Al, Fe	198.3	7.63%		Al recycling Fe recycling
4		Fe	11.8	0.45%		Fe recycling
5	5-1	Complex PCB	754.2	29.00%	The surface of PCB is greater than 10 square centimeters;	
	5-2	Fe	27.0	1.04%		Fe recycling
	5-3	Zn	37.5	1.44%		Zn recycling
6			645.8	24.84%		
7		Zn, Fe	24.0	0.92%		Zn recycling Fe recycling
8	8-1	Zn	37.9	1.46%		Zn recycling
	8-2	Zn	93.3	3.59%		Zn recycling
	8-3	Fe	7.5	0.29%		Fe recycling
	8-4	Zn	143.4	5.51%		Zn recycling
9		PC	0.1	0.01%		Pla recycling

4.0 Revised record

Date	Version	Author	Modify content
2015.05.21	V0	Zhao Jiawen	Initial version